

# PHOTOCOUPLER

# PS2561-1,PS2561L-1,PS2561L1-1,PS2561L2-1

## HIGH ISOLATION VOLTAGE SINGLE TRANSISTOR TYPE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

## DESCRIPTION

The PS2561-1 is optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2561-1 is in a plastic DIP (Dual In-line Package) and the PS2561L-1 is lead bending type (Gull-wing) for surface mount.

The PS2561L1-1 is lead bending type for long creepage distance.

The PS2561L2-1 is lead bending type for long creepage distance (Gull-wing) for surface mount.

#### FEATURES

- High Isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage (VCEO = 80 V)
- High current transfer ratio (CTR = 200 % TYP.)
- High-speed switching (tr = 3  $\mu$ s TYP., tr = 5  $\mu$ s TYP.)
- Ordering number of taping product: PS2561L-1-E3, E4, F3, F4, PS2561L2-1-E3, E4
- ★ Safety standards
  - UL approved: File No. E72422
  - CSA approved: No. CA 101391
  - BSI approved: No. 7112/7420
  - SEMKO approved: No. 303059, 307244
  - NEMKO approved: No. P03200272, P03200747
  - DEMKO approved: No. 312341, 312340
  - FIMKO approved: No. FI 10620, FI 11898
  - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

#### **APPLICATIONS**

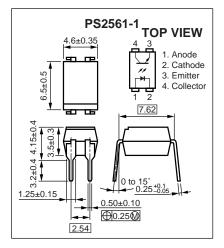
- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

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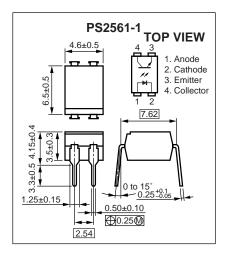
Document No. PN10234EJ03V0DS (3rd edition) Date Published March 2006 CP(K)

## PACKAGE DIMENSIONS (UNIT : mm)

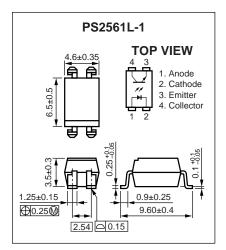
## DIP Type (New package)



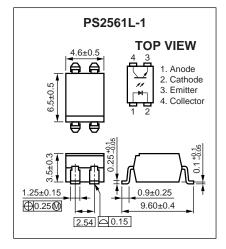
## **DIP** Type

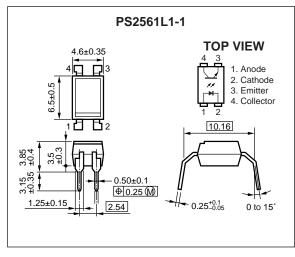


## Lead Bending Type (New package)



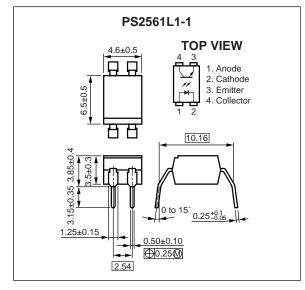
## Lead Bending Type

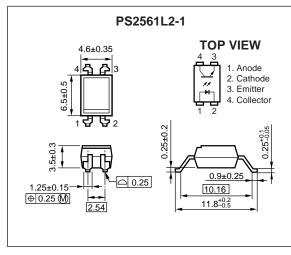




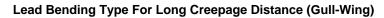
## Lead Bending Type For Long Creepage Distance (New Package)

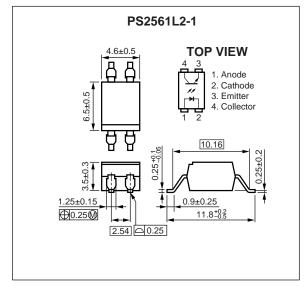
#### Lead Bending Type For Long Creepage Distance



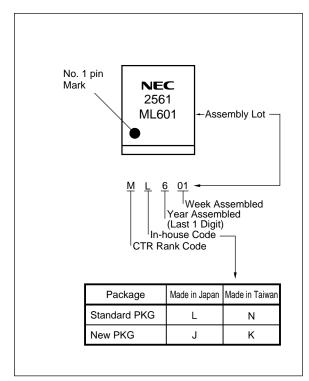


Lead Bending Type For Long Creepage Distance (Gull-Wing) (New Package)





#### **\*** MARKING EXAMPLE



Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS2561-1	PS2561-1-A	Pb-Free	Magazine case 100 pcs	Standard products	PS2561-1
PS2561L-1	PS2561L-1-A			(UL, CSA, BSI,	
PS2561L1-1	PS2561L1-1-A			NEMKO, SEMKO,	
PS2561L2-1	PS2561L2-1-A			DEMKO, FIMKO	
PS2561L-1-E3	PS2561L-1-E3-A		Embossed Tape 1 000 pcs/reel	approved)	
PS2561L-1-E4	PS2561L-1-E4-A				
PS2561L-1-F3	PS2561L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2561L-1-F4	PS2561L-1-F4-A				
PS2561L2-1-E3	PS2561L2-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561L2-1-E4	PS2561L2-1-E4-A				
PS2561-1-V	PS2561-1-V-A		Magazine case 100 pcs	DIN EN60747-5-2	
PS2561L-1-V	PS2561L-1-V-A			(VDE0884 Part2)	
PS2561L1-1-V	PS2561L1-1-V-A			approved products	
PS2561L2-1-V	PS2561L2-1-V-A			(Option)	
PS2561L-1-V-E3	PS2561L-1-V-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561L-1-V-E4	PS2561L-1-V-E4-A				
PS2561L-1-V-F3	PS2561L-1-V-F3-A		Embossed Tape 2 000 pcs/reel	]	
PS2561L-1-V-F4	PS2561L-1-V-F4-A				
PS2561L2-1-V-E3	PS2561L2-1-V-E3-A		Embossed Tape 1 000 pcs/reel	]	
PS2561L2-1-V-E4	PS2561L2-1-V-E4-A				

## **\*** ORDERING INFORMATION

\*1 For the application of the Safety Standard, following part number should be used.

	Parameter	Symbol	Ratings	Unit
Diode	Reverse Voltage	Vr	6	V
	Forward Current (DC)	lf	80	mA
	Power Dissipation Derating	⊿Po/°C	1.5	mW/°C
	Power Dissipation	PD	150	mW
	Peak Forward Current <sup>*1</sup>	IFP	1	А
Transistor	Collector to Emitter Voltage	Vceo	80	V
	Emitter to Collector Voltage	Veco	7	V
	Collector Current	lc	50	mA
	Power Dissipation Derating	⊿Pc/°C	1.5	mW/°C
	Power Dissipation	Pc	150	mW
Isolation Voltage <sup>*2</sup>		BV	5 000	Vr.m.s.
Operating Ambient Temperature		TA	–55 to +100	°C
Storage Temperature		Tstg	-55 to +150	°C

## ★ ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)

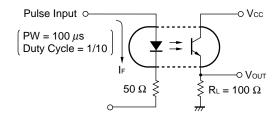
\*1 PW = 100 µs, Duty Cycle = 1%

\*2 AC voltage for 1 minute at  $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

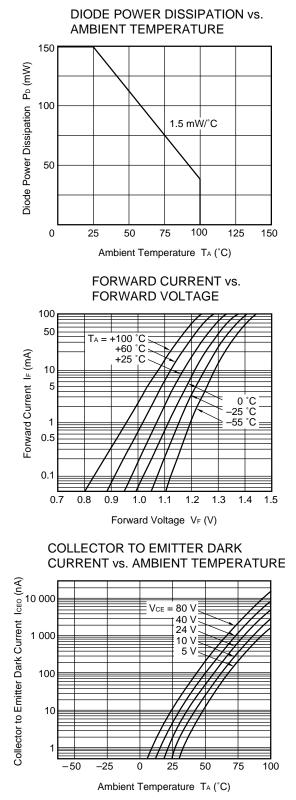
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.17	1.4	V
	Reverse Current	Ir	V <sub>R</sub> = 5 V			5	μA
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	Iceo	$V_{CE} = 80 \text{ V}, \text{ IF} = 0 \text{ mA}$			100	nA
Coupled	Current Transfer Ratio (Ic/IF) <sup>*1</sup>	CTR	IF = 5 mA, VCE = 5 V	80	200	400	%
	Collector Saturation Voltage	VCE (sat)	IF = 10 mA, Ic = 2 mA			0.3	V
	Isolation Resistance	R⊦o	VI-O = 1.0 kVDC	10 <sup>11</sup>			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time <sup>*2</sup>	tr	$V_{CC}$ = 10 V, Ic = 2 mA, RL = 100 $\Omega$		3		μS
	Fall Time <sup>*2</sup>	tr			5		

## ELECTRICAL CHARACTERISTICS (TA = 25°C)

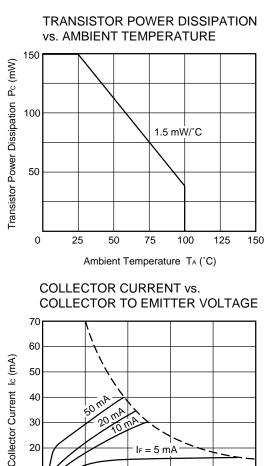
- ★ \*1 CTR rank
  - L : 200 to 400 (%)
  - M : 80 to 240 (%)
  - D : 100 to 300 (%)
  - H : 80 to 160 (%)
  - W: 130 to 260 (%)
  - \*2 Test circuit for switching time

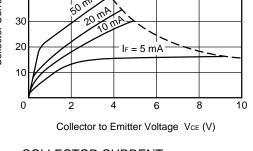


## ★ TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, unless otherwise specified)

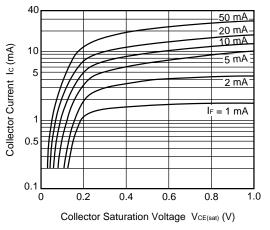


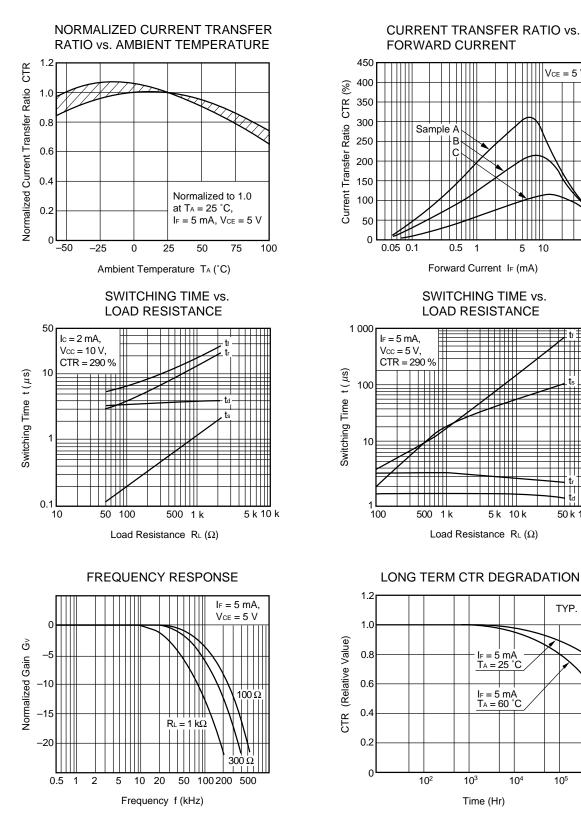






COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE





Remark The graphs indicate nominal characteristics.

Data Sheet PN10234EJ03V0DS

Vce = 5 V

50

50 k 100 k

TYP.

105

Sample A

С

0.5

500 1 k

1

Forward Current I<sub>F</sub> (mA)

SWITCHING TIME vs.

5k 10k

I⊧ = 5 mA T<sub>A</sub> = 25 °C

l⊧ = 5 mA Ta = 60 °C

10<sup>4</sup>

10<sup>3</sup>

Time (Hr)

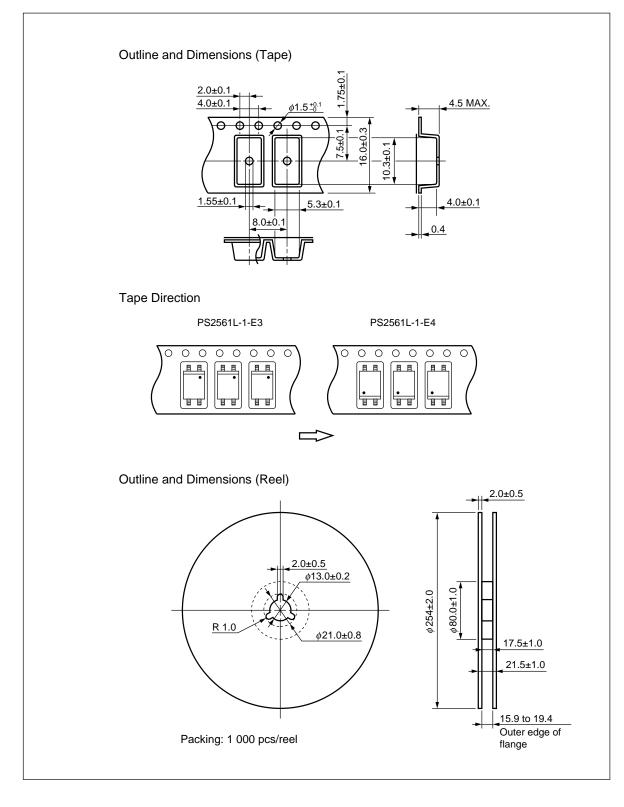
10<sup>2</sup>

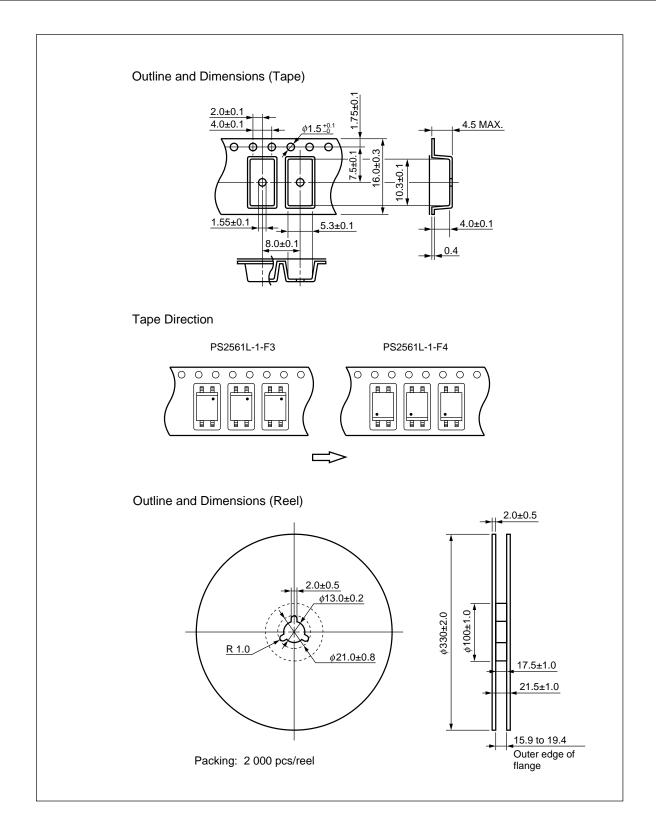
Load Resistance RL (Ω)

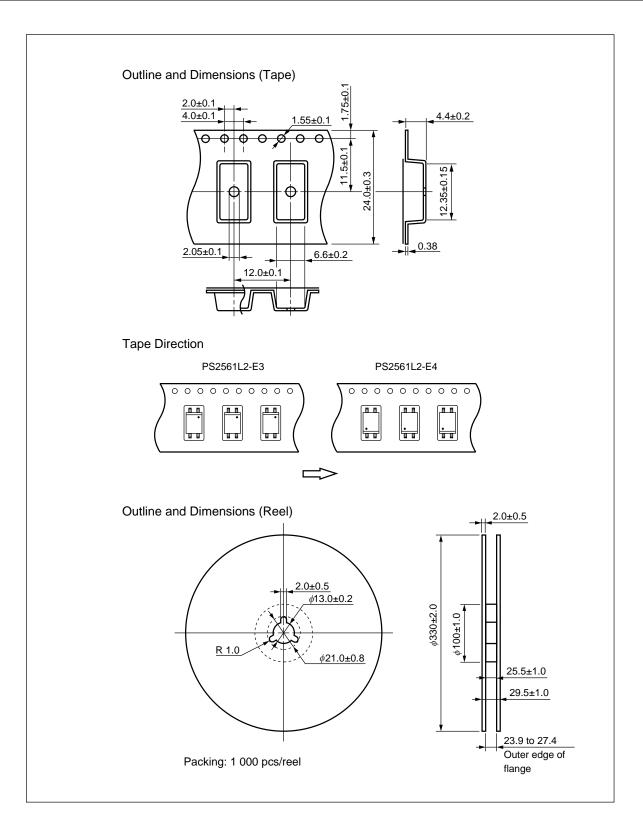
LOAD RESISTANCE

5 10

## \* TAPING SPECIFICATIONS (UNIT : mm)







#### NOTES ON HANDLING

#### 1. Recommended soldering conditions

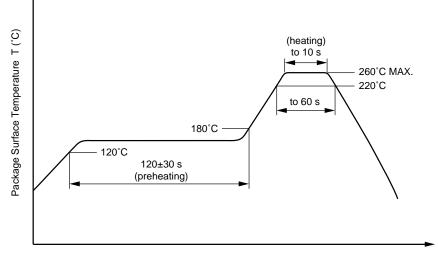
#### (1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to  $180^\circ\text{C}$
- Number of reflows
- Flux

10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

260°C or below (package surface temperature)

#### Recommended Temperature Profile of Infrared Reflow



Time (s)

#### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### ★ (3) Soldering by soldering iron

<ul> <li>Peak temperature (lead part temperature)</li> </ul>	350°C or below
<ul> <li>Time (each pins)</li> </ul>	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

#### (4) Cautions

#### Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

#### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

#### \* 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below  $I_F = 1$  mA.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

## USAGE CAUTIONS

1. Protect against static electricity when handling.

2. Avoid storage at a high temperature and high humidity.

Parameter	Symbol	Speck	Unit
Application classification (DIN VDE 0109) for rated line voltages $\leq$ 300 Vr.m.s. for rated line voltages $\leq$ 600 Vr.m.s.		IV III	
Climatic test class (DIN IEC 68 Teil 1/09.80)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.2 \times U_{IORM}$ , $P_d < 5 \ pC$	Uiorm Upr	890 1 068	V <sub>peak</sub> V <sub>peak</sub>
Test voltage (partial discharge test, procedure b for all devices test) $U_{pr}$ = 1.6 x U <sub>IORM</sub> , Pd < 5 pC	Upr	1 424	Vpeak
Highest permissible overvoltage	Utr	8 000	Vpeak
Degree of pollution (DIN VDE 0109)		2	
Clearance distance		> 7.0	mm
Creepage distance		> 7.0	mm
Comparative tracking index (DIN IEC 112/VDE 0303 part 1)	CTI	175	
Material group (DIN VDE 0109)		lll a	
Storage temperature range	Tstg	-55 to +150	°C
Operating temperature range	TA	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25 \text{ °C}$ $V_{IO} = 500 \text{ V dc at } T_A MAX. at least 100 \text{ °C}$	Ris MIN. Ris MIN.	10 <sup>12</sup> 10 <sup>11</sup>	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current IF, Psi = 0) Power (output or total power dissipation) Isolation resistance	Tsi Isi Psi	175 400 700	°C mA mW
Vio = 500 V dc at T <sub>A</sub> = 175 °C (Tsi)	Ris MIN.	10 <sup>9</sup>	Ω

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M8E 00.4-0110

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	<ol> <li>Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> </ol>
	<ol><li>Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol>
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

►For further information, please contact	
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0504



Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (\*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A -AZ Not Detected (*)		
Mercury	< 1000 PPM	Not De	etected	
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not De	etected	
РВВ	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

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